Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	17685	b23k026\$.ipc.	JPO	OR	ON	2006/08/05 09:37
L2	146	L1 and (curv\$5 with (hold\$3 support\$3 chuck\$3 table bed surface))	JPO	OR	ON	2006/08/05 09:38
L3	129	L2 and laser	JPO	OR	ON	2006/08/05 09:37
L4	1104	L1 and ((curv\$5 arcuate arc round\$3 spher\$7 shape\$2) with (hold\$3 support\$3 chuck\$3 table bed surface stage clamp\$3)) and laser	JPO	OR	ON	2006/08/05 11:00
L5	776	L1 and ((curv\$5 arcuate arc round\$3 spher\$7 shape\$2) with (hold\$3 support\$3 chuck\$3 table bed surface stage clamp\$3)) and ((curv\$5 arcuate arc round\$3 spher\$7 shape\$2) with laser)	JPO	OR	ON	2006/08/05 09:44
L6	325	L1 and ((curv\$5 arcuate arc round\$3 spher\$7 shape\$2) near3 (hold\$3 support\$3 chuck\$3 table bed surface stage clamp\$3)) and ((curv\$5 arcuate arc round\$3 spher\$7 shape\$2) with laser)	JPO	OR	ON	2006/08/05 09:45
L7	116	L1 and ((curv\$5 arcuate arc round\$3 spher\$7) near3 (hold\$3 support\$3 chuck\$3 table bed surface stage clamp\$3)) and ((curv\$5 arcuate arc round\$3 spher\$7 shape\$2) with laser)	JPO	OR -	ON	2006/08/05 09:45
L8	105	L1 and ((curv\$5 arcuate arc round\$3 spher\$7) near3 (hold\$3 support\$3 chuck\$3 table bed surface stage clamp\$3)) and ((curv\$5 arcuate arc round\$3 spher\$7) with laser)	JPO	OR	ON	2006/08/05 09:46
L9	98	L1 and ((curv\$5 arcuate arc round\$3 spher\$7) near3 (hold\$3 support\$3 chuck\$3 table bed surface stage clamp\$3)) and ((curv\$5 arcuate arc round\$3 spher\$7) with laser) not (arc adj weld\$4) not (arc adj discharg\$5)	JPO	OR	ON	2006/08/05 10:37
L11	2	"20040155019"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/05 10:38

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L12	1	11 and (focal adj length) with condenser with curvature	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/05 10:42
L15	1	11 and y with x	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2006/08/05 10:46
L17	1	11 and y	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/05 10:55
L18	9	(("5643826") or ("6246524") or ("6137633") or ("6176926") or ("6104535") or ("6304385") or ("6300176") or ("5858822") or ("6077731")).PN.	USPAT; USOCR	OR	OFF	2006/08/05 10:56
L19	8	18 and stage	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/05 11:34
L20	3	18 and stage with (curv\$7 arcuate cylind\$6 spher\$7)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/05 11:00
L21	10	L1 and ((curv\$5 arcuate arc round\$3 spher\$7 shape\$2) with (hold\$3 support\$3 chuck\$3 table bed surface stage clamp\$3)) and laser and anneal\$5	ЈРО	OR	ON	2006/08/05 11:04
L22	20	L1 and ((curv\$5 arcuate arc round\$3 spher\$7 shape\$2)) and laser and anneal\$5 not 21	JPO	OR	ON	2006/08/05 11:10
L23	68	L1 and ((curv\$5 arcuate arc round\$3 spher\$7 shape\$2) with (silicon wafer semiconductor))	JPO	OR	ON	2006/08/05 11:11
L24	5	L1 and ((curv\$5 arcuate arc round\$3 spher\$7) with (silicon wafer semiconductor))	JPO	OR	ON	2006/08/05 11:12
L25	13	L1 and ((bend\$4 bent warp\$4) with (silicon wafer semiconductor))	JPO	OR	ON	2006/08/05 11:29

126		I de la	100	0.0	ON	2006/00/05 11 21
L26	4	L1 and (concav\$5 with (silicon wafer semiconductor))	JPO	OR	ON	2006/08/05 11:31
L27	3	L1 and (concav\$5 and (silicon wafer semiconductor)) not 26	JPO	OR	ON	2006/08/05 11:32
L28	1620	(concav\$5 with (silicon wafer semiconductor)) same (stage support\$4 platform hold holding holder)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR ·	ON	2006/08/05 11:35
L29	869	(silicon wafer semiconductor) same (stage support\$4 platform hold holding holder) near5 concav\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/05 11:35
L30	29	(silicon wafer semiconductor) same (stage support\$4 platform hold holding holder) near5 concav\$5 same (warp\$4 bend\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/05 12:19
L34	117	(silicon wafer semiconductor) same anneal\$4 and ((stage support\$4 platform hold holding holder) near5 concav\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/05 12:20
L35	95	(silicon wafer semiconductor) with anneal\$4 and ((stage support\$4 platform hold holding holder) near5 concav\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/05 12:20
L36	4	(silicon wafer semiconductor) with anneal\$4 and ((stage support\$4 platform hold holding holder) near5 concav\$5 same laser)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/05 12:22
L37	0	(silicon wafer semiconductor) same anneal\$4 same ((stage support\$4 platform hold holding holder) near5 concav\$5 same laser)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/05 12:23
L38		(silicon wafer semiconductor) same anneal\$4 and ((stage support\$4 platform hold holding holder) near5 concav\$5 same laser)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/05 12:24
L39	112	(silicon wafer semiconductor) same anneal\$4 and ((stage support\$4 platform hold holding holder) near5 concav\$5) not 38	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/05 12:24

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L40	5	(silicon wafer semiconductor) same anneal\$4 same ((stage support\$4 platform hold holding holder) near5 concav\$5) not 38	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/05 12:29
L41	28453	"269"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/05 12:29
L42	27	41 and concav\$4 with (wafer silicon)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR.	ON	2006/08/05 12:38
L43	9256	(wafer silicon) same (lithograph\$5 pattern fabrication) same (anneal\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/05 12:39
L44	725	(wafer silicon) same (lithograph\$5 pattern fabrication) same (anneal\$4) same (chuck stage table support)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/05 12:40
L45	- 5	(wafer silicon) same (lithograph\$5 pattern fabrication) same (anneal\$4) same (chuck stage table support) same (concav\$4 convex\$4 cylindrical\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/05 12:47
L46	205	(wafer silicon) same (lithograph\$5 pattern fabrication) same (anneal\$4) and ((chuck stage table support) same (concav\$4 convex\$4 cylindrical\$4)) not 45	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2006/08/05 12:47
L47	13	(wafer silicon) same (lithograph\$5 pattern fabrication) same (anneal\$4) and ((chuck stage table support) same (concav\$4 convex\$4 cylindrical\$4) same anneal\$4) not 45	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/05 12:52
L48	18	(wafer silicon) with laser with (anneal\$4) and ((chuck stage table support) same (concav\$4 convex\$4 cylindrical\$4) with anneal\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/05 12:53
L49	1	("5907770").PN.	USPAT; USOCR	OR	OFF	2006/08/05 12:54

L51	1	49 and (concav\$4 convex\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/05 12:55
L52	1	49 and (concav\$4 convex\$4) with stage	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/05 13:00
·L53	1	18 and (concav\$4 convex\$4) with stage	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/05 13:01
L54	0	18 and concav\$4 with stage	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/05 13:01